UNITED STATES SECURITIES AND EXCHANGE COMMISSION

Washington, D.C. 20549

FORM 8-K

CURRENT REPORT Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): June 21, 2011

TTM TECHNOLOGIES, INC.

(Exact name of registrant as specified in its charter)

DELAWARE	0-31285	91-1033443
(State or other Jurisdiction of Incorporation)	(Commission File Number)	(IRS Employer Identification No.)
2630 SOUTH HARBOR BOU SANTA ANA, CALIFOR		92704
(Address of Principal Executive Offices) (Zip Code)		(Zip Code)
Registrant's	telephone number, including area code: (7	714) 327-3000
(Former i	name or former address if changed since le	ast report.)
Check the appropriate box below if the Forunder any of the following provisions:	m 8-K filing is intended to simultaneously	satisfy the filing obligation of the registrant
☐ Written communications pursuant to Rul	e 425 under the Securities Act (17 CFR 2)	30.425)
☐ Soliciting material pursuant to Rule 14a-	12 under the Exchange Act (17 CFR 240.	14a-12)
☐ Pre-commencement communications pur	rsuant to Rule 14d-2(b) under the Exchang	ge Act (17 CFR 240.14d-2(b))
□ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))		

Item 7.01. Regulation FD Disclosure.

We are filing this Current Report on Form 8-K in connection with the disclosure of textual information from a slide show presentation given at the NASDAQ OMX 26th Investor Program on June 21, 2011. A copy of this slide show presentation is being furnished as Exhibit 99.1 to this Current Report on Form 8-K.

The information in this Current Report (including the exhibit) is furnished pursuant to Item 7.01 and shall not be deemed to be "filed" for the purpose of Section 18 of the Securities Exchange Act of 1934, as amended, or otherwise subject to the liabilities of that section. This Current Report will not be deemed an admission as to the materiality of any information in this Current Report that is required to be disclosed solely by Regulation FD.

We do not have, and expressly disclaim, any obligation to release publicly any updates or any changes in our expectations or any change in events, conditions, or circumstances on which any forward-looking statement is based.

The information included with this Current Report (including the exhibit) will be available at our website located at www.ttmtech.com, although we reserve the right to discontinue that availability at any time.

The information in this Report includes references to "EBITDA." EBITDA means earnings before interest expense, income taxes, depreciation and amortization. We present EBITDA to enhance the understanding of our operating results. EBITDA is a key measure we use to evaluate our operations. In addition, we provide our EBITDA because we believe that investors and securities analysts will find EBITDA to be a useful measure for evaluating our operating performance and comparing our operating performance with that of similar companies that have different capital structures and for evaluating our ability to meet our future debt service, capital expenditures and working capital requirements. However, EBITDA should not be considered as an alternative to cash flows from operating activities as a measure of liquidity or as an alternative to net income as a measure of operating results in accordance with accounting principles generally accepted in the United States.

Item 9.01. Financial Statements and Exhibits.

(d) Exhibits.

99.1 Slides presented at the NASDAQ OMX 26th Investor Program on June 21, 2011.

SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

TTM TECHNOLOGIES, INC.

Date: June 21, 2011 By: /s/ Steven W. Richards

Steven W. Richards Chief Financial Officer

TTM Technologies Investor Presentation



Global Presence Local Knowledge

NASDAQ OMX 26th Investor Program
June 21, 2011

Safe Harbor

During the course of this presentation, the company will make forward-looking statements subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements. Such risks and uncertainties include, but are not limited to, fluctuations in quarterly and annual operating results, the volatility and cyclicality of various industries that the company serves and other risks described in TTM's most recent SEC filings. The company assumes no obligation to update the information provided in this presentation.

The company also will present non-GAAP financial information in this presentation. For a reconciliation of TTM's non-GAAP financial information to the equivalent measures under GAAP, please refer to the company's press release, which was filed with the SEC and which is posted on TTM's website.

Company Overview



Global Leader in PCB Manufacturing

- Top 5 global PCB manufacturer \$1.4 billion in revenue*
- 15 specialized factories located in U.S. and China
- Over 17,000 employees worldwide
- Focused on advanced technology products
- Total customer solution: prototype through production
- Technology development coordinated with customers' needs
- Diversified end markets with broad customer base

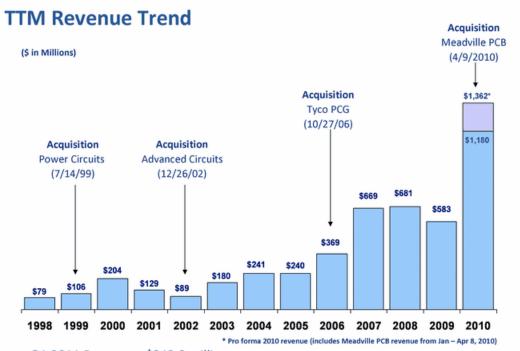
* Pro forma 2010



Q1 2011 Highlights

- Sales \$342.8 million
- Gross margin: 23.9%
- GAAP net income¹: \$27.1 million \$0.33 per diluted share
- Non-GAAP net income¹: \$33.3 million \$0.40 per diluted share
- Lead times at normal levels: 4 6 weeks

¹ Net income attributable to shareholders



- Q1 2011 Revenue \$342.8 million
- Target average growth of 15% over the long term

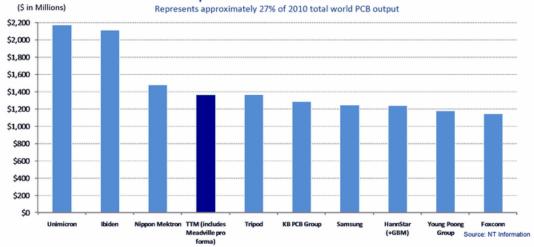
TTM Technologies

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Specialized Facilities Provide Optimal Growth Integrated manufacturing platform enables TTM to execute a global facility specialization strategy China **United States** Aerospace/Defense High Tech/Quick-Turn/High Mix Focused Assembly Volume Production Substrate 1 Stafford, CT Chippewa Falls, WI Shanghai, China Dongguan - DMC 3 Shanghai - SMST Stafford Springs, CT 1 Dongguan – SYE 2 Santa Clara, CA Santa Ana, CA Guangzhou – GME 3 San Diego, CA 6 Logan, UT 7 Hong Kong - OPCM B Shanghai - SME ■ Suzhou – MAS TTM Technologies







Leading Position in Growing Market Segments

- Core supplier to wide range of high-end networking products addressing increasing bandwidth demands
- Key supplier in rapidly growing touch screen tablet market
- Expanding position in smartphones
- Leadership position in strategic North America Aerospace & Defense industry

TTM Technologies

Global Strength

Asia Pacific

- 7 factories / 3.5 million sq. ft.
- Over 30 million sq. ft. of capacity (annual)
- Strong in Smartphones, Tablet PCs, Servers, Storage and Networking
- Ramp and Volume capability
- · Advanced "any layer" HDI
- · High layer count conventional PCB
- Flex & rigid-flex PCB
- Substrate PCB

North America

- 8 factories / 850k sq. ft.
- · Over 3 million sq. ft. of capacity (annual)
- Strong in Aerospace & Defense, High End Servers, Storage and Networking
- Proto, Ramp and Low Volume/ High Mix production
 - Very high layer count capability
 - Specialty rigid-flex, RF and thermal management PCBs
 - Advanced HDI for commercial and defense

Combined Strength, Total Solution

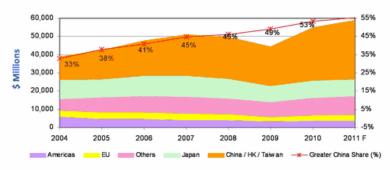
TTM Technologies

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Industry & Market Overview



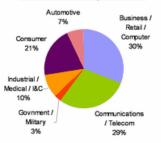
World PCB Outlook



- · 55% of the world production will be generated from the Greater China region in 2011
- · China will continue to gain share in the world PCB production

Source: N.T. Information Ltd. April, 2011

2011 PCB Demand by End Market

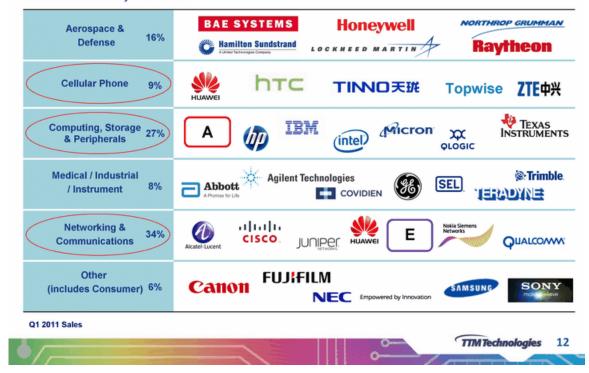


End Market Demand	Worldwide	Asia	North America
Life market Demand	11 - 14 CAGR	11 - 14 CAGR	11 -14 CAGR
Business / Retail / Computer	10.9%	13.6%	4.7%
Communications / Telecoms	11.0%	14.2%	4.7%
Consumer	10.9%	11.2%	3.9%
Industrial / Medical / I&C	8.4%	15.1%	4.5%
Automotive	7.3%	10.4%	3.8%
Government / Military	5.2%	8.5%	4.3%
Total	10.3%	13.0%	4.5%

Source: BPA Consulting, Feb 2011

Diversified End Market & Customer Base

Selected Customers by End Market



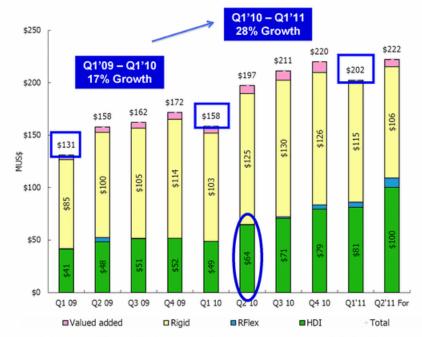
Future Plans & Strategies





Advanced Technology, Value Added Strategy Maturity R&D Early involvement High Volume engineering support High Mix / Low Volume TTM Technologies Advanced **Product Technology & Service NPI** Excellence Launch/ Ramp Prototype / QTA Pilot orders Low volume / High mix (NA) Medium volume / Ramp (AP) High technology Volume production (AP) TTIM Technologies

Growth Driver - Asia Pacific



- Seasonality in Q1 with gradual improvement into Q2
- Launch of touchpad tablets in Q2 2010
- Continuous growth in demand for smartphones
- Continued demand for increased bandwidth
- Focus on more advanced HDI applications

Technology & ASP



High Density Interconnect (HDI) Technology

Strategic Growth Objectives

- Invest in advanced technology
- Focus on the early stages of the product life cycle
- Leverage our leadership position and global footprint
- Service customers in growth end markets
- Customer-driven culture



Financial Overview



Consolidated Income Statement – Q1 Actual

\$ Millions (except where noted)	Asia Pacific	North America	Total
Revenue	\$200.6	\$142.2	\$342.8
Gross Profit	50.8 25.3%	31.1 21.9%	81.9 23.9%
Operating Income	29.7 14.8%	16.0 11.3%	45.7 13.3%
Net Income*	19.1 9.5%	8.0 5.6%	27.1 7.9%
GAAP Diluted EPS* \$ per share	0.23	0.10	0.33
EBITDA	46.0 22.9%	20.5 14.4%	66.5 19.4%

^{*} Attributable to stockholders; excludes net income of \$2.0M attributable to noncontrolling interests

Target Model

(\$ in millions, except EPS)
Revenue
Gross Profit
Gross Margin
Operating Income
Operating Margin
GAAP Diluted EPS*
Non-GAAP Diluted EPS*
Operating Cash Flow
Operating Cash Flow
Free Cash Flow

	2011	
4Q 2010	Q1	Q2 Est.
\$373.4	\$342.8	\$350 - \$370
\$90.0	\$81.9	\$75 - \$85
24.1%	23.9%	21% - 23%
\$52.6	\$45.7	\$39 - \$48
14.1%	13.3%	11% - 13%
\$0.41	\$0.33	\$0.28 - \$037
\$0.49	\$0.40	\$0.36 - \$0.45
\$89.2	\$37.1	
\$50.2	\$10.6	

Annual Target Model
15% Growth
25%
15%

^{*} Attributable to stockholders

Balance Sheet

(\$ in millions)	December 31, 2010	March 28, 2011
(\$ III IIIIIIOIIS)	2010	2011
Assets:		
Cash, Cash Equivalents and Short-term Investments	\$216.1	\$202.3
Accounts and Notes Receivable, Net	287.7	292.0
Inventories	135.4	144.6
Other Current Assets	37.3	40.6
Total Current Assets	676.5	679.5
Property, Plant & Equipment	876.2	910.9
Accumulated Depreciation	(135.6)	(150.5)
Property, Plant and Equipment, Net	740.6	760.4
Goodwill	197.8	197.3
Definite-lived Intangibles, Net	97.9	93.4
Other Assets	49.2	58.3
Total Assets	\$1,762.0	\$1,788.9
Liabilities and Equity:		
Current Portion Long-Term Debt	67.1	87.5
Accounts Payable	154.6	161.8
Accounts Payable Due to Related Parties	50.4	42.2
Accrued Salaries, Wages and Benefits	51.1	43.3
Other Accrued Expenses	95.0	114.9
Total Current Liabilities	418.2	449.7
Convertible Senior Notes, Net	145.3	146.7
Long-Term Debt, Less Current Portion	313.0	260.6
Other Long-Term Liabilities	52.6	56.7
Total Liabilities	929.1	913.7
TTM Technologies, Inc. Stockholders' Equity	728.3	768.3
Noncontrolling Interest	104.6	106.9
Total Equity	832.9	875.2
Total Liabilities and Equity	\$1,762.0	\$1,788.9

Cash Flow

		YTD
(\$ in millions)	2010	March 28, 2011
Net Income	\$79.9	\$29.1
Depreciation of Property, Plant and Equipment	48.7	15.7
Amortization of Definite-Lived Intangible Assets	13.8	4.2
Amortization of Convertible Notes, Debt Discount and Debt Issuance Costs	6.8	1.8
Deferred Income Taxes	15.2	6.7
Stock-Based Compensation	6.9	1.8
Impairment of Goodwill and Long-Lived Assets	0.8	0.0
Other Operating Activities	0.7	(8.0)
Working Capital Changes:		
Accounts and Notes Receivable, Net	(65.6)	(4.2)
Inventories	(8.8)	(9.2)
Prepaid Expenses and Other Current Assets	(10.4)	(4.3)
Accounts Payable	9.0	1.1
Accrued Salaries, Wages and Benefits and Other Accrued Expenses	28.8	(4.8)
Cash Flow from Operations	125.8	37.1
Acquisition, Net of Cash Acquired	(28.5)	0.0
Restricted Cash Movements	120.0	0.0
Net Capital Expenditures	(59.9)	(26.5)
Proceeds from Short-Term Investments	1.4	0.0
Other Investing Activities	0.0	0.0
Cash Flow from Investing Activities	33.0	(26.5)
Proceeds from Exercise of Stock Options	2.1	2.1
Repayment of Revolving Loan and Long-Term Debt	(38.0)	(32.1)
Other Financing Activities	0.5	5.5
Cash Flow from Financing Activities	(35.4)	(24.5)
Free Cash Flow	\$65.9	\$10.6

Investment Highlights

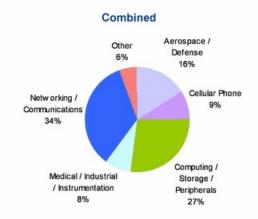
- Market leader in advanced technology PCBs
- Strong track record of operating performance
- Increasing margin profile
- Highly efficient operations and low cost structure
- · Healthy balance sheet
- Solid cash flow funding growth

Appendix



Diversified End Markets

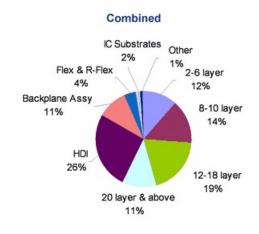
	AP	NA
Aerospace / Defense	0%	39%
Cellular Phone	15%	0%
Computing / Storage / Peripherals	38%	11%
Medical / Industrial / Instrument	5%	12%
Networking / Communications	33%	37%
Other	9%	1%



1Q 2011 Sales

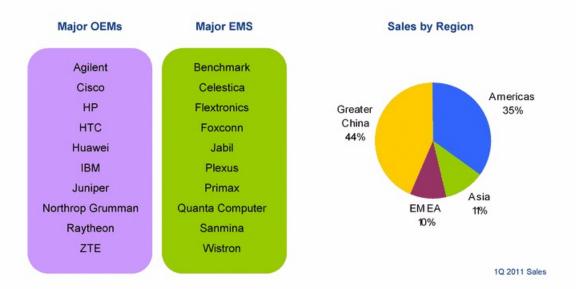
Broad Product Offering

	AP	NA
2 – 6 Layer	12%	11%
8 – 10 Layer	18%	10%
12 – 18 Layer	20%	18%
20 Layer +	4%	21%
HDI	40%	7%
Backplane Assembly	0%	26%
Flex & Rigid-Flex	2%	6%
IC Substrates	3%	0%
Other	1%	1%



1Q 2011 Sales

Global Revenue Base



TTIM Technologies

Reconciliations

		YTD
(\$ in millions, except EPS)	2010	March 28, 2011
EBITDA Reconciliation:		
Net Income	\$79.9	\$29.1
Add Back Items:		
Income Tax Provision	28.7	11.3
Interest Expense	22.3	6.3
Depreciation Expense	48.7	15.6
Amortization of Intangibles	13.8	4.2
EBITDA	\$193.4	\$66.5
Non-GAAP EPS Reconciliation:		
Net Income Attributable to Stockholders	\$71.5	\$27.1
Add Back Items:		
Amortization of Intangibles	13.8	4.2
Stock-Based Compensation	6.9	1.8
Non-Cash Interest Expense	7.7	2.2
Impairment, Restructuring and Other Charges	17.8	0.0
Income Tax Effects	(12.2)	(2.0)
Non-GAAP net income attributable to stockholders	\$105.5	\$33.3
Non-GAAP earnings per diluted share attributable		
to stockholders	\$1.49	\$0.40
Diluted Shares	70,819	82,304

IR Contacts

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